

42. A method as claimed in claim 39 wherein said etch-resistant metal includes a metal adapted to facilitate bonding of said posts to contact pads.

43. A method as claimed in claim 39 further comprising the step of providing a support structure on a surface of said sheet opposite from the surface having said conductive portions.

44. A method as claimed in claim 43 wherein said support structure is provided prior to said etching step.

45. A method of treating a component comprising the steps of:

(a) providing a component including a plurality of metallic posts extending generally parallel to one another and having solder on tips of said posts but not covering other portions of said posts; and

(b) reflowing the solder so that the solder coats the posts.

46. A method as claimed in claim 45 wherein said providing step is performed so that, prior to said reflowing step, said solder covers only the tips of said posts.

47. A method as claimed in claim 45 wherein said providing step includes depositing portions of said solder on a surface of a metallic sheet and etching said sheet from said surface.